

/ Descriptions

TO-3P

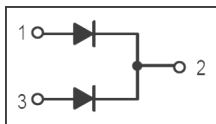
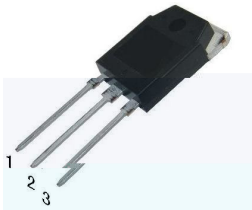
Ultrafast Recovery Diode in a TO-3P Plastic Package.

/ Features

Silicon epitaxial process to produce ultrafast recovery diode with low reverse leakage current and high reliability.

/ Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode

/ Equivalent Circuit**/ Pinning**

PIN1 Anode PIN2 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

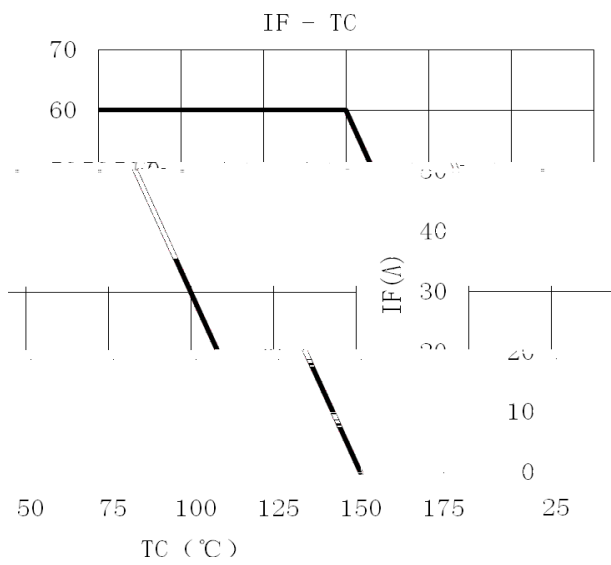
See Marking Instructions

MUR6060PT

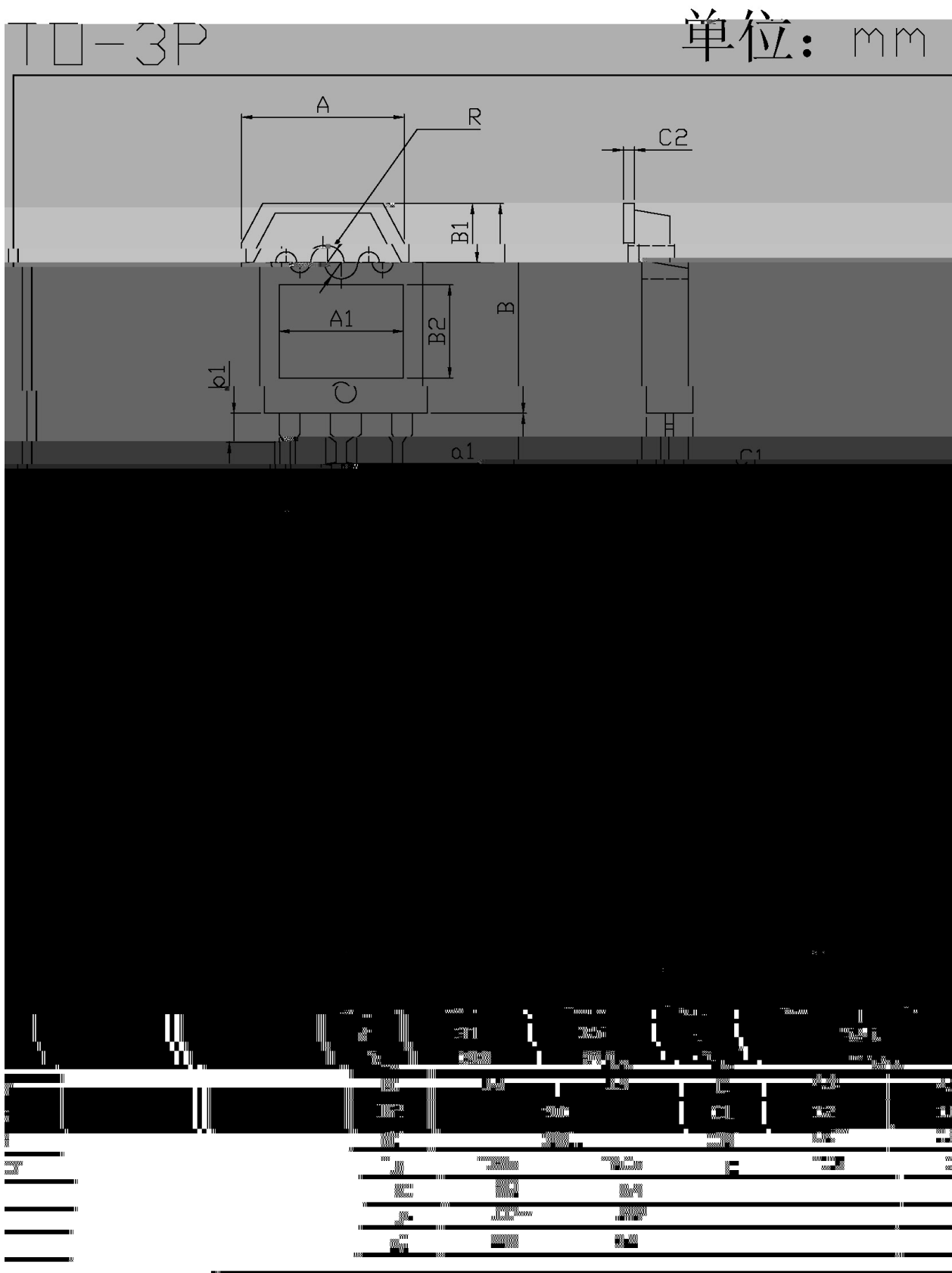
Rev.E Mar.-2016

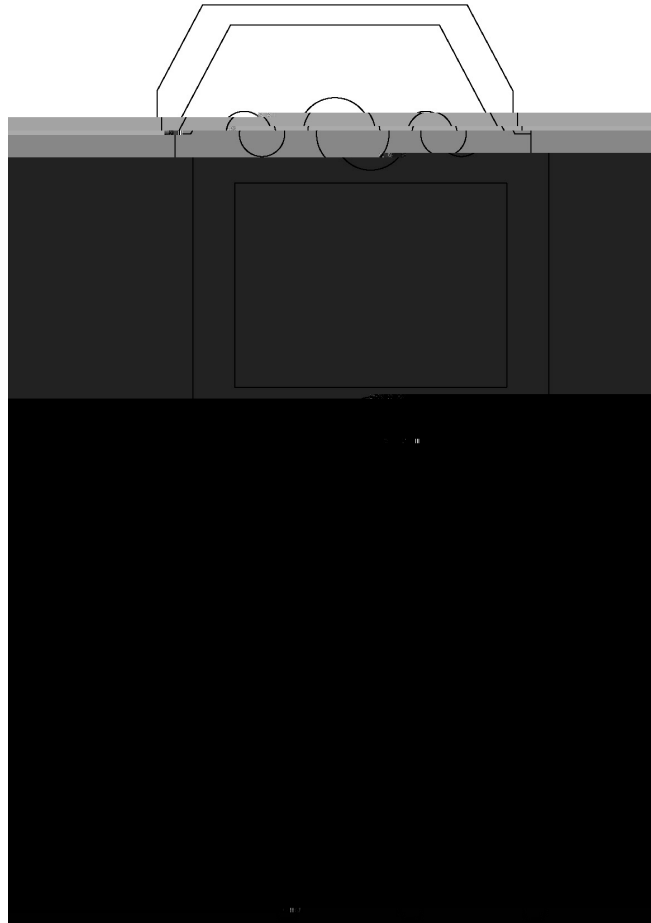
DATA SHEET

/ Electrical Characteristic Curve



/ Package Dimensions





() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;

1.Preheating:25~150 , Time:60~90sec.
- 2

255±5

5±0.5sec;

2.Peak Temp.:255±5 , Duration:5±0.5sec.
- 3

2 10

/sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5

10±1 sec.

Temp.:270±5

Time:10±1 sec

/ Packaging SPEC.

/ TUBE

Package Type	Units					Dimension		(unit mm ³)
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	In8T	